

## DESCRIPTION

The SESRV05-4 is a dual USB port protection array that features ultra low capacitance. This device can be used in applications such as video cards, SMART phones, Gigabit Ethernet and other computer interfaces. Designed for ESD protection, the SESRV05-4 can clamp the effects of electrical fast transients on the power bus.

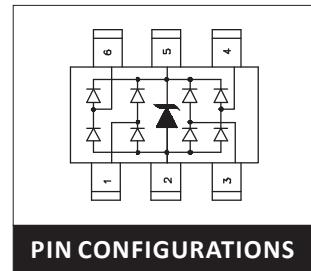
The SESRV05-4 combines 8 low capacitance steering diodes for up to four individual data or transmission lines and one TVS diode for power bus protection. This device is available in the space-saving SOT-23-6 package configuration, which minimizes lead inductance to prevent overshoot voltages during high ESD current events. The SESRV05-4 meets the IEC 61000-4-2, 61000-4-2 and 61000-4-5 requirements.



SOT-23-6 PACKAGE

## FEATURES

- >80 Watts peak pulse power( $tp=8/20\mu s$ )
- >Protects four I/O lines
- >Low clamping voltage
- >Small package: SOT23-6L
- >Low leakage current
- >Weight 16 Milligrams



PIN CONFIGURATIONS

## APPLICATIONS

- >USB 2.0 Power and Data Line Protection
- >Video Graphics Cards
- >Monitors and Flat Panel Displays
- >Digit Video Interface (DVI)
- >10/100/1000 Ethernet
- >Notebook Computers
- >ATM Interfaces

## IEC COMPATIBILITY

- >IEC 61000-4-2(ESD) $\pm 15KV$ (air), $\pm 8KV$ (contact)
- >IEC61000-4-4 (EFT) 40A (5/50ns)
- >IEC61000-4-5 (Lightning) 5A (8/20 $\mu s$ )

## MAXIMUM RATINGS AND CHARACTERISTICS

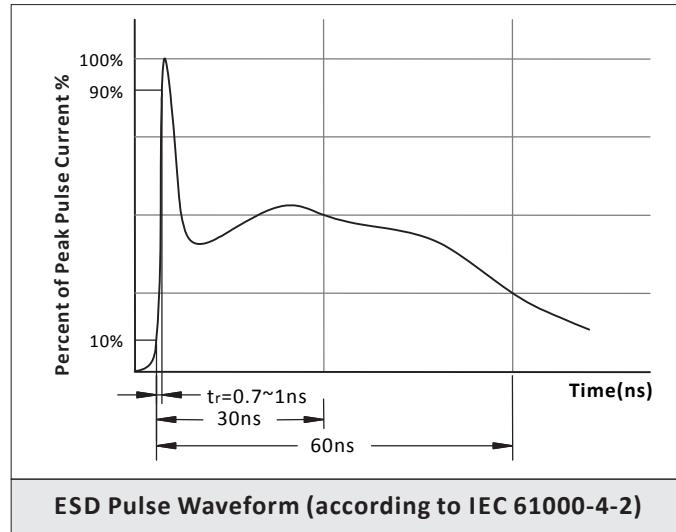
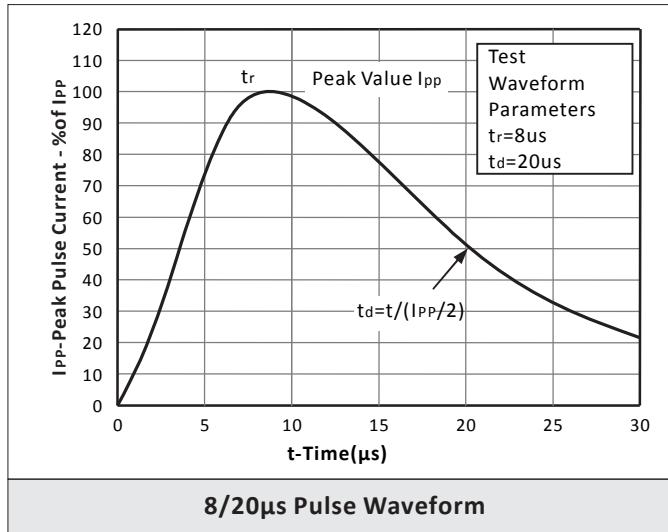
 Ratings at 25°C ambient temperature unless otherwise specified.

MAXIMUM RATINGS @ 25°C UNLESS OTHERWISE SPECIFIED				
PARAMETER		SYMBOL	VALUE	UNIT
Peak Pulse Power ( $tp=8/20\mu s$ waveform)		P <sub>PP</sub>	80	Watts
Operating Temperature Range		T <sub>J</sub>	-55~125	°C
Storage Temperature Range		T <sub>STG</sub>	-55~150	°C

## ELECTRICAL CHARACTERISTICS

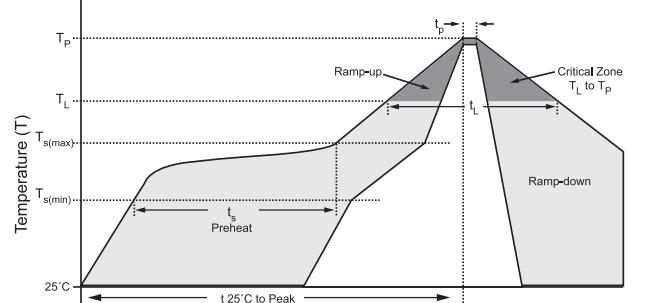
ELECTRICAL CHARACTERISTICS PER LINE @ 25°C UNLESS OTHERWISE SPECIFIED											
PART NUMBER	DEVICE MARKING	V <sub>RWM</sub> (V) Max.	V <sub>B</sub> (V) Min.	I <sub>T</sub> (mA)	V <sub>C</sub> @1A Max.	V <sub>C</sub>		I <sub>R</sub> (uA) Max.	C <sub>T</sub> I/O-GND (pF) Typ.	C <sub>T</sub> I/O-I/O (pF) Typ.	
SESRV05-4	V05	5.0	6.0	1	12.5	17.5	@A	5	1	0.8	0.4

## CHARACTERISTIC CURVES

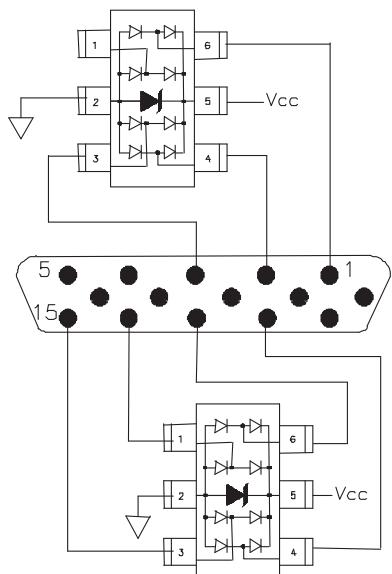


## REFLOW PROFILE

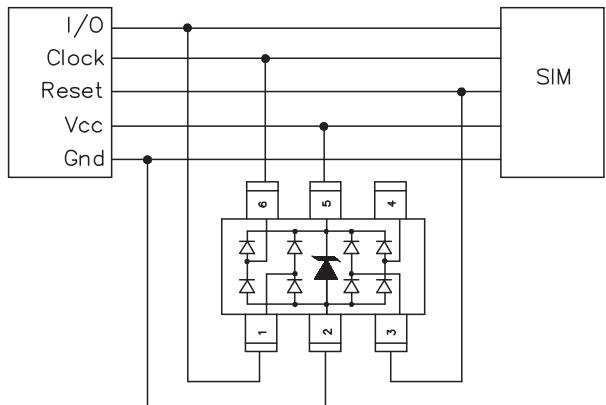
Reflow Condition		Lead-free assembly
Pre Heat	Temperature Min ( $T_s(\text{min})$ )	150°C
	Temperature Max ( $T_s(\text{max})$ )	200°C
	Time (min to max) ( $t_s$ )	60 – 180 secs
Average ramp up rate (Liquidus Temp ( $T_L$ ) to peak)		3°C/second max
$T_s(\text{max})$ to $T_L$ - Ramp-up Rate		3°C/second max
Reflow	Temperature ( $T_L$ ) (Liquidus)	217°C
	Time (min to max) ( $t_L$ )	60 – 150 seconds
Peak Temperature ( $T_P$ )		260°C
Time within 5°C of actual peak Temperature ( $t_p$ )		20 – 40 seconds
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature ( $T_P$ )		8 minutes Max.
Do not exceed		260°C



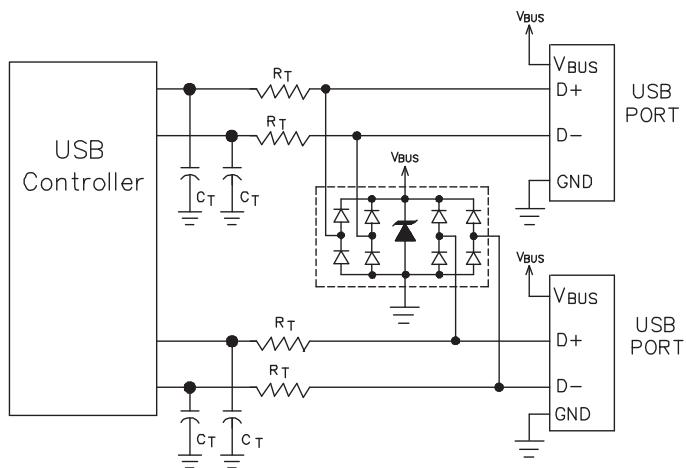
## TYPICAL APPLICATIONS



Video Interface Protection

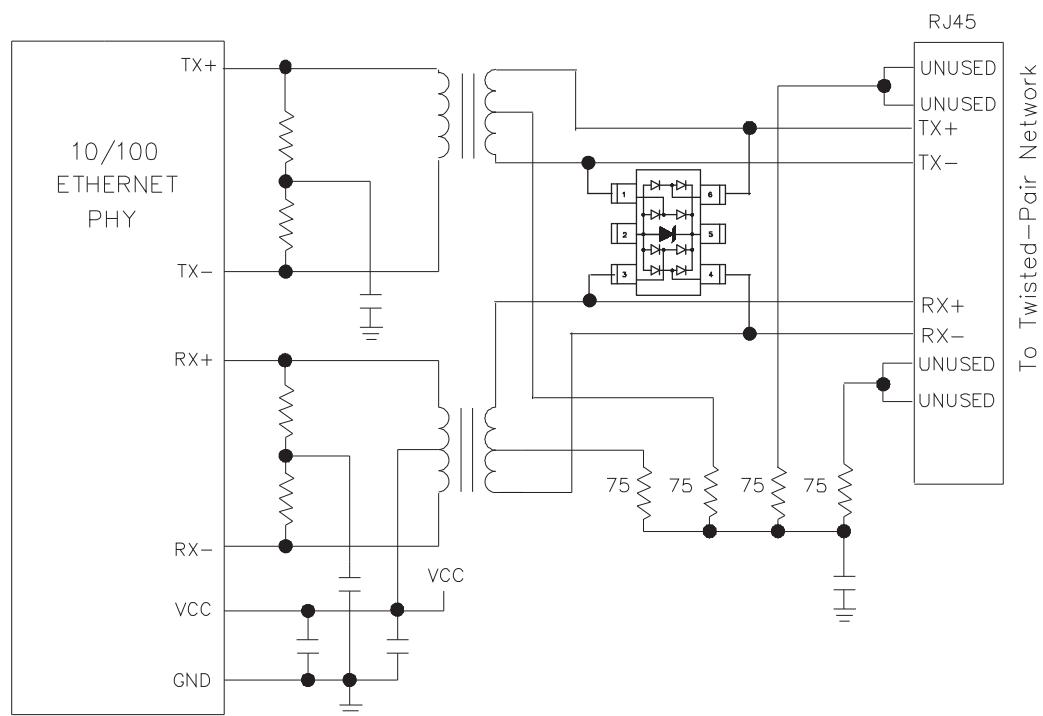
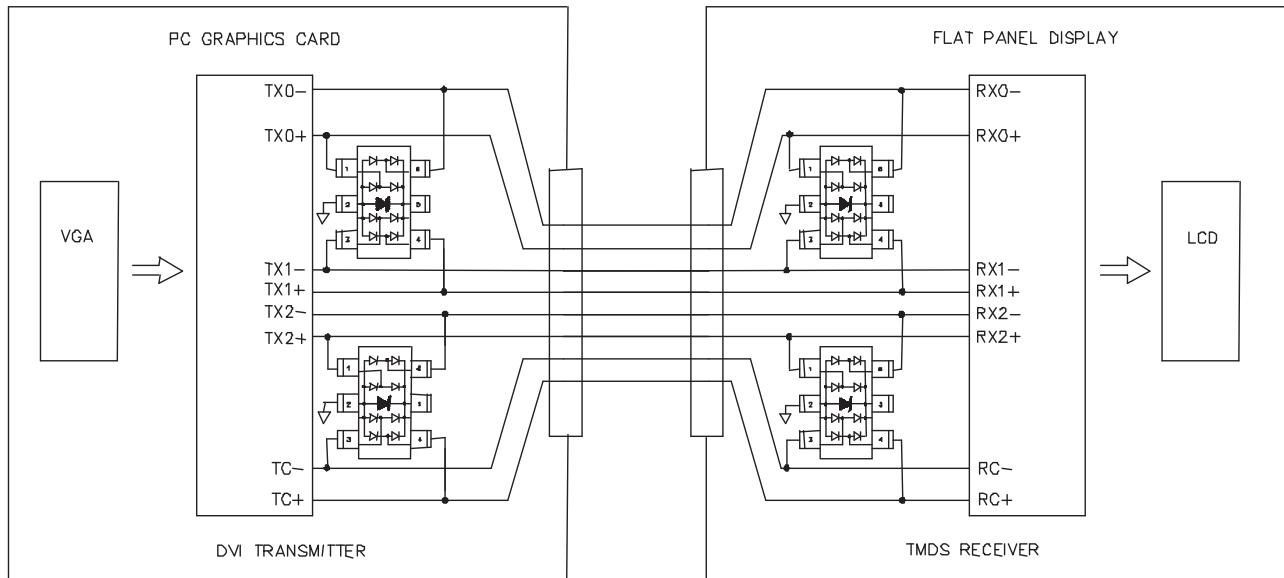


SIM Port

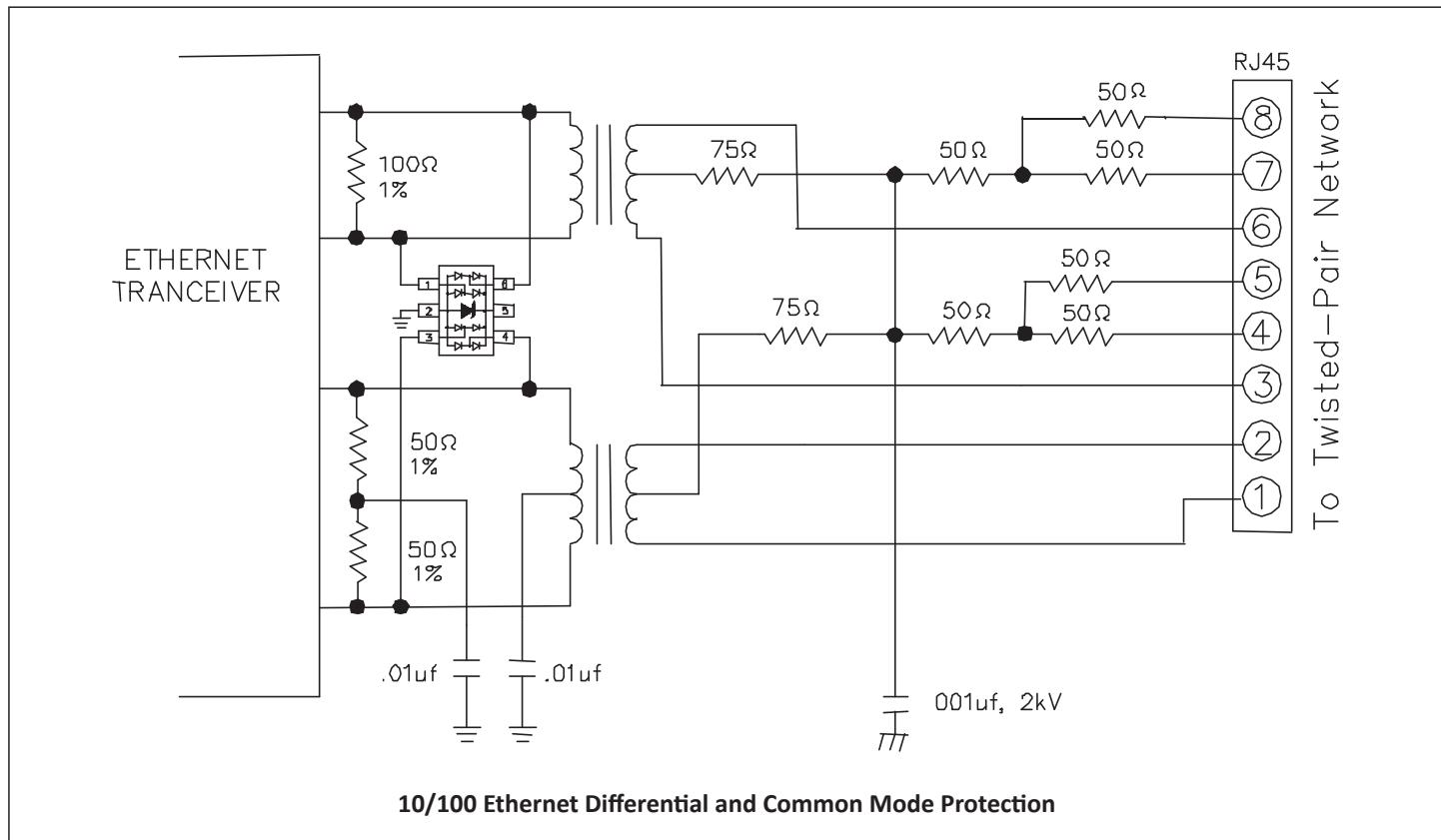


Dual USB Port Protection

### TYPICAL APPLICATIONS

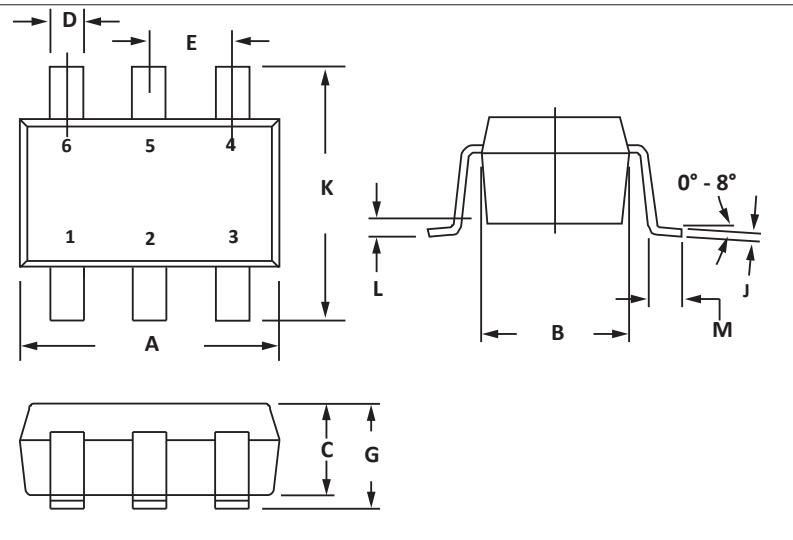


## TYPICAL APPLICATIONS



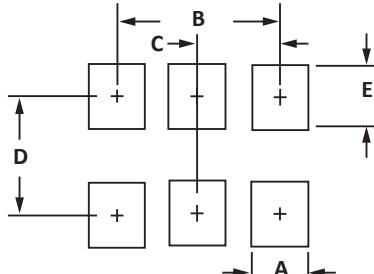
## SOT-23-6 PACKAGE INFORMATION

DIM	OUTLINE DIMENSIONS			
	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	2.80	3.05	0.110	0.120
B	1.50	1.75	0.059	0.070
C	0.90	1.30	0.036	0.051
D	0.30	0.40	0.012	0.016
E	0.85	1.05	0.033	0.040
G	0.90	1.45	0.036	0.057
J	0.09	0.20	0.003	0.008
K	2.60	3.00	0.102	0.118
L	0.0	0.15	0.0	0.006
M	0.30	0.60	0.012	0.024



## RECOMMENDED PAD LAYOUT DIMENSIONS

DIM	PAD LAYOUT DIMENSIONS	
	MILLIMETERS	
	NOMINAL	NOMINAL
A	0.70	0.028
B	1.90	0.074
C	0.95	0.037
D	2.40	0.094
E	1.00	0.039



## ORDERING INFORMATION

Part Number	Component Package	QTY/Reel	Reel Size
SESRV05-4	SOT-23-6	3000PCS	7"

## CONTACT US

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